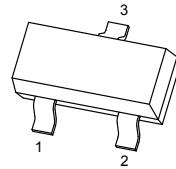


SOT-23 Plastic-Encapsulate MOSFETs

20V P-Channel MOSFET

$V_{(BR)DSS}$	$R_{DS(on)}\text{Typ}$	$I_D \text{ Max}$
-20V	70mΩ@4.5V	-3.0A
	78mΩ@3.3V	

SOT-23



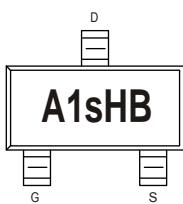
Features

Trench FET Power MOSFET

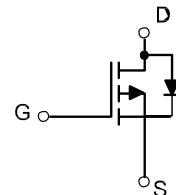
APPLICATION

- Load Switch for Portable Devices
- DC/DC Converter

MARKING



Equivalent circuit



PACKAGE SPECIFICATIONS

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (pcs)	Box Size (mm)	QTY/Box (pcs)	Carton Size (mm)	Q'TY/Carton (pcs)
SOT-23	7'	330	3000	203×203×195	45000	438×438×220	180000

Maximum Ratings and Thermal Characteristics (TA = 25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	±10	
Continuous Drain Current $T_A = 25^\circ\text{C}$	I_D	-3.0	A
$T_A = 70^\circ\text{C}$		-2.5	
Pulsed Drain Current ¹⁾	I_{DM}	-12	A
Maximum Power Dissipation ²⁾ $T_A = 25^\circ\text{C}$	P_D	1.2	W
$T_A = 70^\circ\text{C}$		0.9	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-50 to 150	°C
Junction-to-Ambient Thermal Resistance (PCB mounted) ²⁾	R_{thJA}	100	°C/W

Notes

¹⁾ Pulse width limited by maximum junction temperature.²⁾ Surface Mounted on FR4 Board, t ≤ 5 sec.

The above data are for reference only.

MOSFET ELECTRICAL CHARACTERISTICS

 $T_a=25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Static						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-20			V
Gate-source threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-0.4	-0.6	-1	
Gate-source leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 10\text{V}$			± 100	nA
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}} = -20\text{V}, V_{\text{GS}} = 0\text{V}$			-1	μA
Drain-source on-state resistance ^a	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -4.5\text{V}, I_D = -3\text{A}$		70	90	$\text{m}\Omega$
		$V_{\text{GS}} = -3.3\text{V}, I_D = -2.0\text{A}$		78	100	
Forward transconductance ^a	g_f	$V_{\text{DS}} = -5\text{V}, I_D = -2.8\text{A}$		4.0		S
Dynamic^b						
Input capacitance	C_{iss}	$V_{\text{DS}} = -10\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		330		pF
Output capacitance	C_{oss}			50		
Reverse transfer capacitance	C_{rss}			45		
Total gate charge	Q_g	$V_{\text{DS}} = -10\text{V}, V_{\text{GS}} = -4.5\text{V}, I_D = -3\text{A}$		6.6		nC
Gate-source charge	Q_{gs}	$V_{\text{DS}} = -10\text{V}, V_{\text{GS}} = -4.5\text{V}, I_D = -3\text{A}$		0.8		
Gate-drain charge	Q_{gd}			0.7		
Turn-on delay time	$t_{\text{d}(\text{on})}$			1.4		
Rise time	t_r	$V_{\text{DD}} = -10\text{V}, R_L = 10\Omega, I_D = -3\text{A}, V_{\text{GEN}} = -4.5\text{V}, R_g = 3.3\Omega$		11		ns
Turn-off delay time	$t_{\text{d}(\text{off})}$			12		
Fall time	t_f			18		
				30		
Drain-source body diode characteristics						
Continuous source-drain diode current	I_s	$T_C = 25^\circ\text{C}$			-1.5	A
Body diode voltage	V_{SD}	$I_s = -2\text{A}$		-0.85	-1.2	V

^{a)} Pulse test: pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$ ^{b)} Guaranteed by design, not subject to production testing

Typical Characteristics

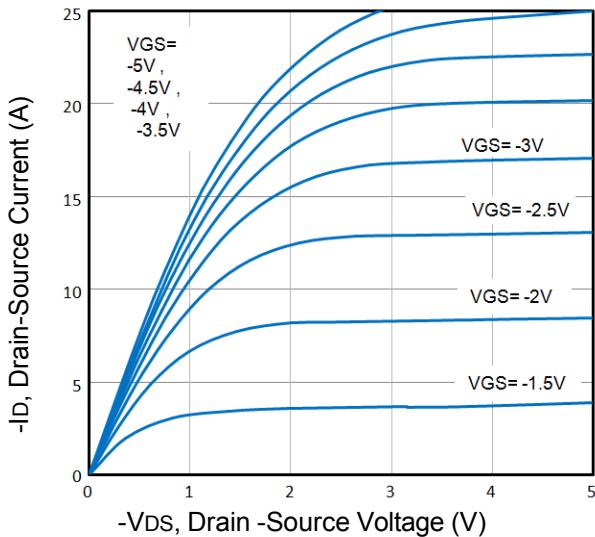


Fig1. Typical Output Characteristics

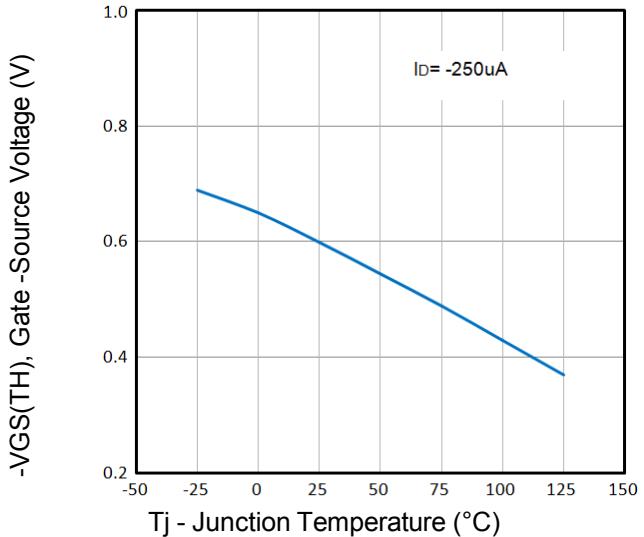


Fig2. Normalized Threshold Voltage Vs. Temperature

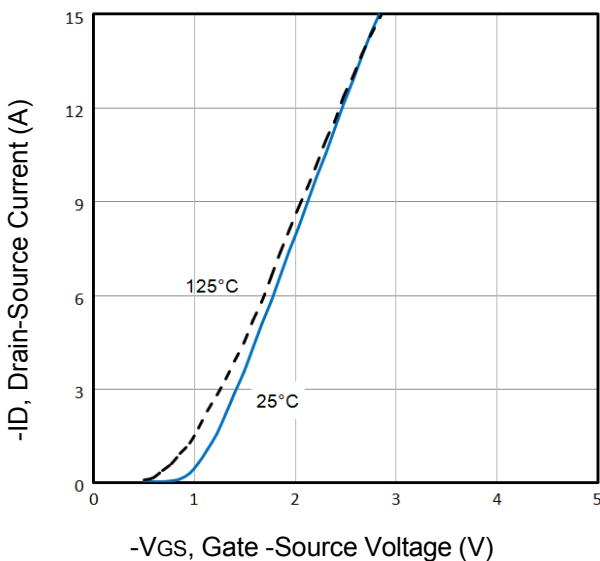


Fig3. Typical Transfer Characteristics

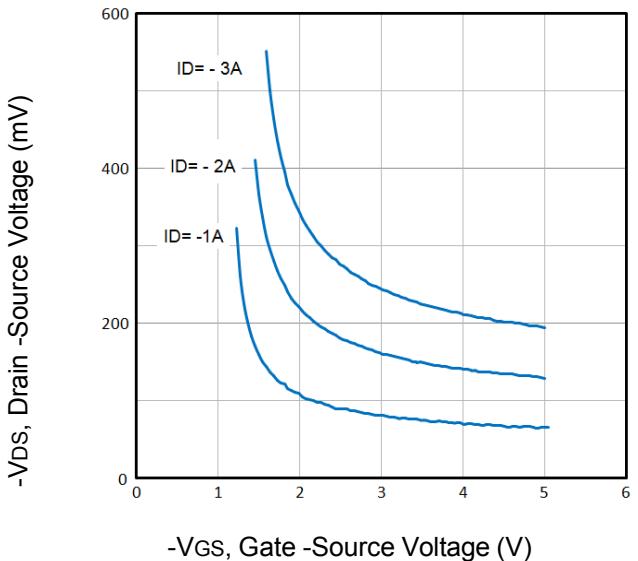


Fig4. Drain -Source Voltage vs Gate -Source Voltage

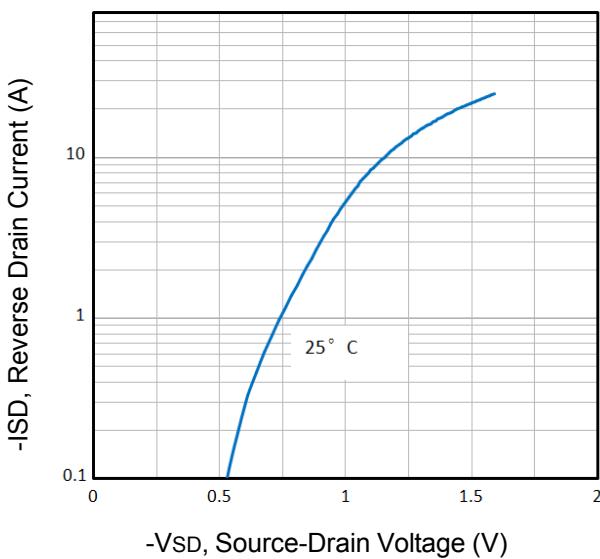


Fig5. Typical Source-Drain Diode Forward Voltage

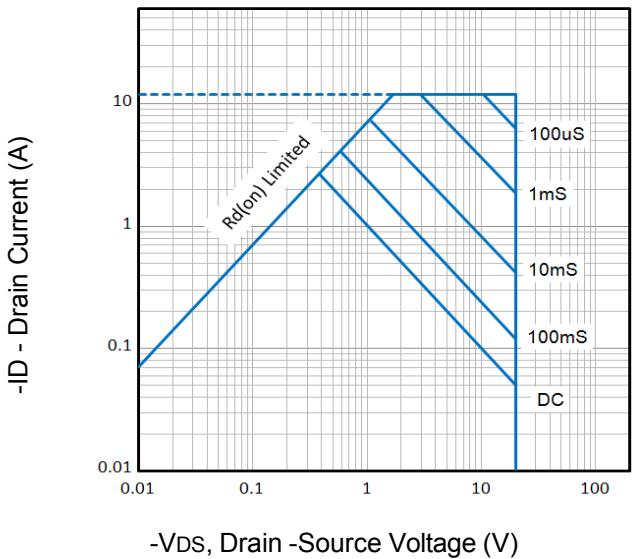


Fig6. Maximum Safe Operating Area

Typical Characteristics

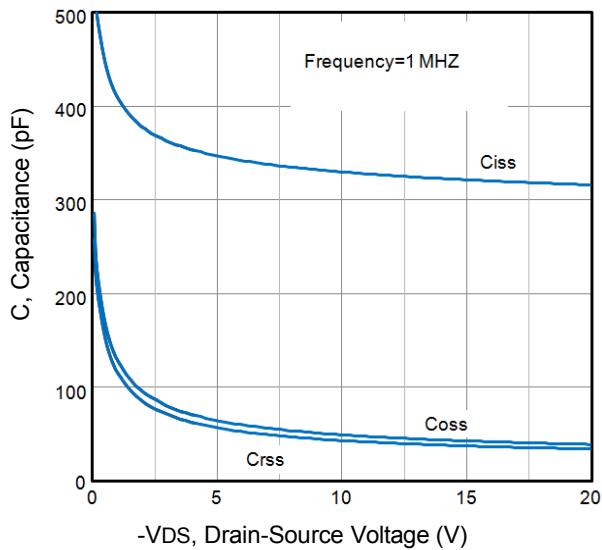


Fig7. Typical Capacitance Vs. Drain-Source Voltage

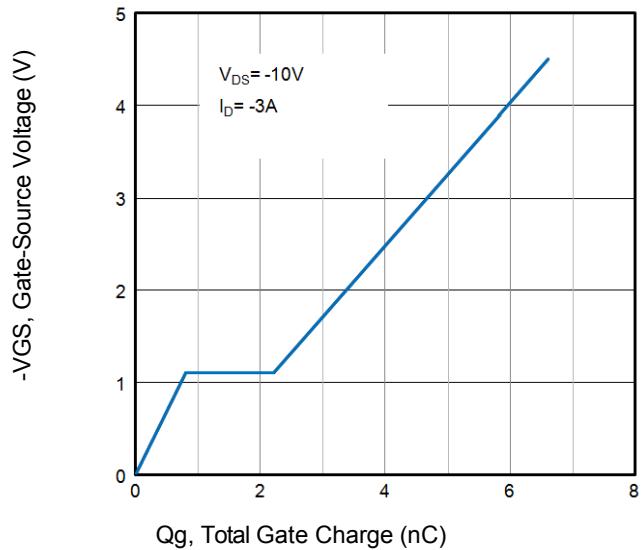


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

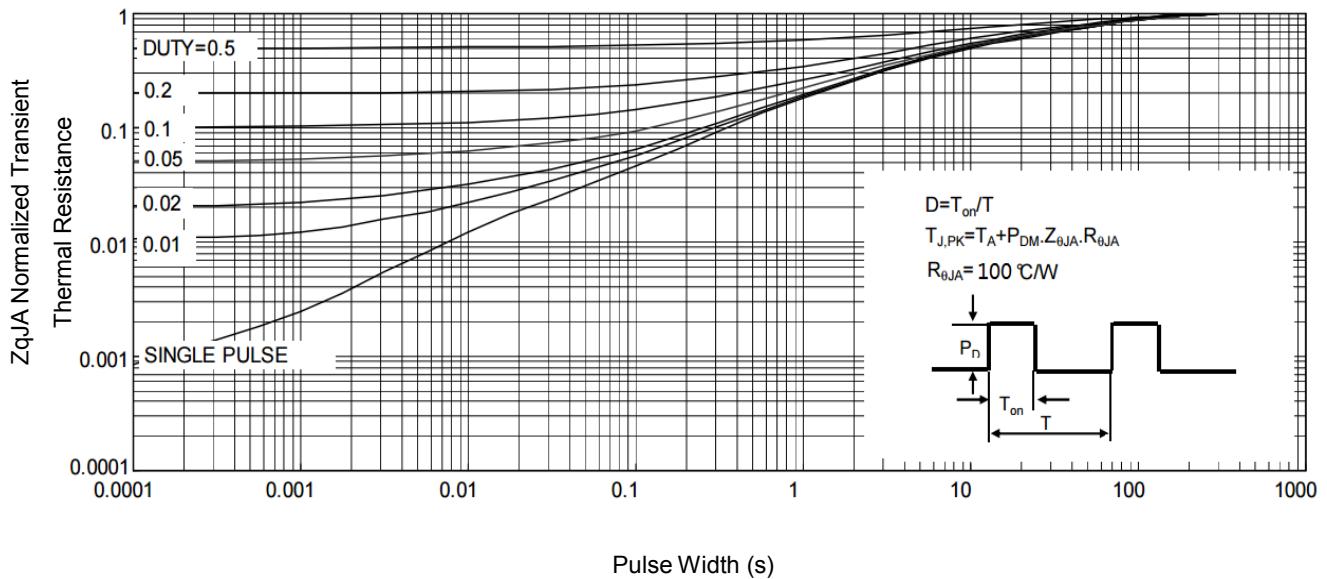


Fig9. Normalized Maximum Transient Thermal Impedance

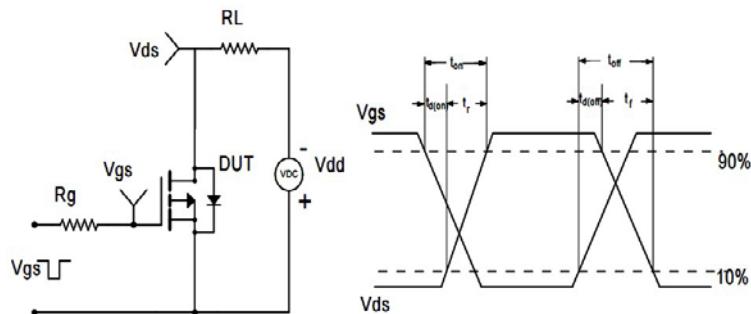
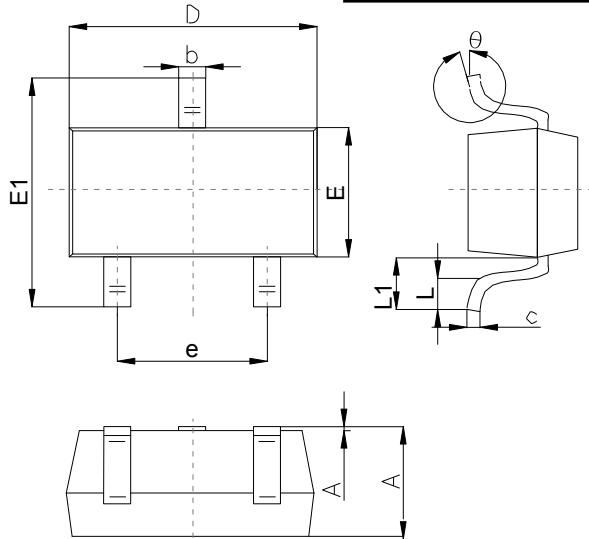


Fig10. Switching Time Test Circuit and waveforms

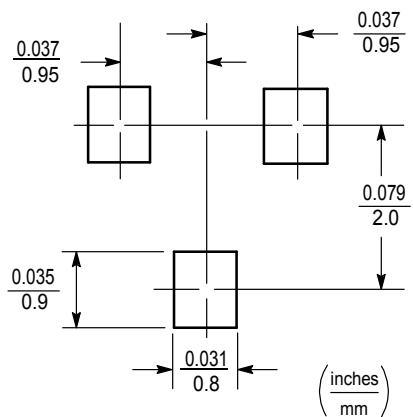
Outline Drawing

SOT-23 Package Outline Dimensions



Symbol	Dimensions In Millimeters		
	Min	Typ	Max
A	1.00		1.40
A1			0.10
b	0.35		0.50
c	0.10		0.20
D	2.70	2.90	3.10
E	1.40		1.60
E1	2.4		2.80
e		1.90	
L	0.10		0.30
L1	0.4		
θ	0°		10°

Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.